

MA3X198 (MA198)

Silicon epitaxial planar type

For wave detection

■ Features

- Two elements contained in one package, allowing high-density mounting
- Soft recovery characteristic ($t_{rr} = 100$ ns)

■ Package

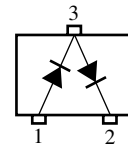
- Code
Mini3-G1
- Pin Name
1: Anode 1
2: Cathode 2
3: Cathode 1, Anode 2

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Repetitive peak reverse voltage	V_{RRM}	40	V
Forward current (Average)	Single	100	mA
	Series		
Repetitive peak forward current	Single	225	mA
	Series		
Non-repetitive peak forward surge current*	Single	500	mA
	Series		
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Marking Symbol: M2F

■ Internal Connection



Note) *: $t = 1$ s

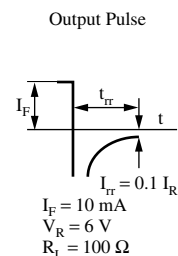
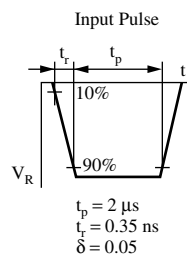
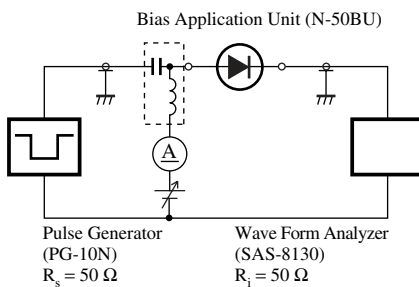
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 100 \mu\text{A}$	0.65		0.72	V
	V_{F2}	$I_F = 100 \text{mA}$			1.2	V
Reverse current	I_R	$V_R = 40 \text{V}$			10	nA
Terminal capacitance	C_t	$V_R = 6 \text{V}, f = 1 \text{MHz}$		1.0	2.0	pF
Reverse recovery time*	t_{rr}	$I_F = 10 \text{mA}, V_R = 6 \text{V}$ $I_{rr} = 0.1 I_R, R_L = 100 \Omega$			100	ns

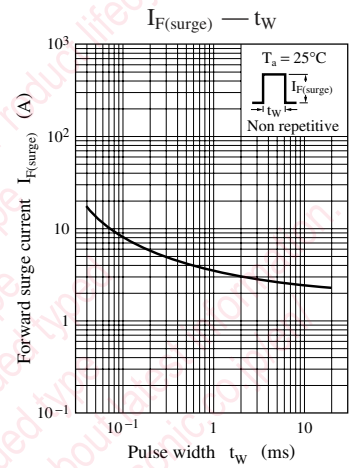
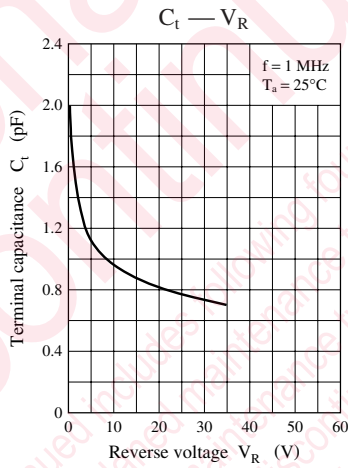
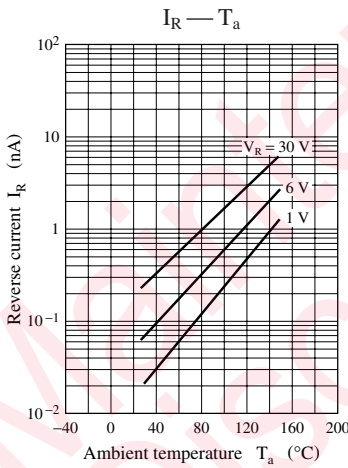
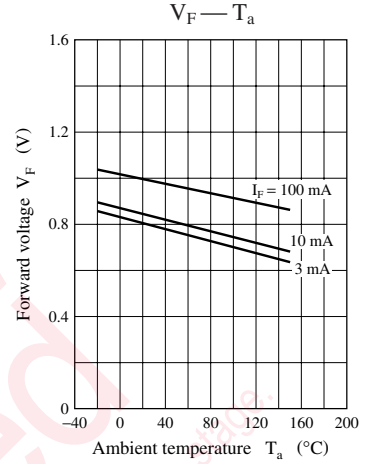
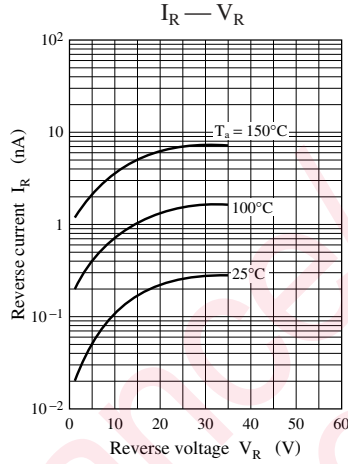
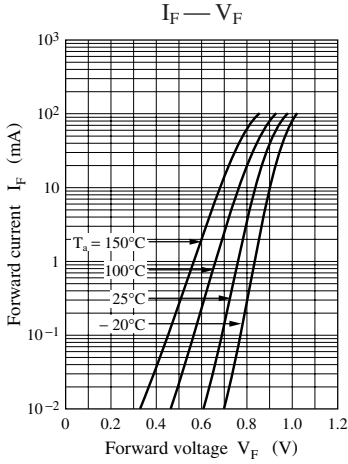
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 10 MHz.

3. *: t_{rr} measurement circuit

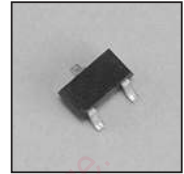
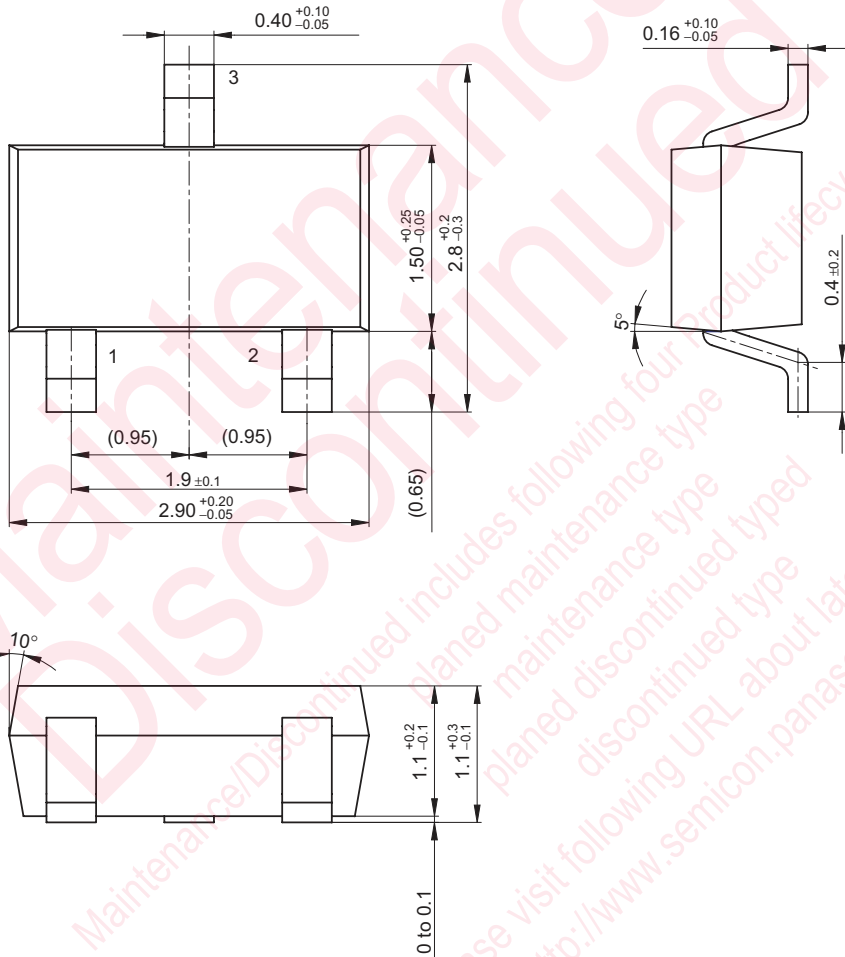


Note) The part number in the parenthesis shows conventional part number.



Mini3-G1

Unit: mm



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